



Nanofluids and Their Applications

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Message from the Guest Editors

Dear Colleagues,

Nanofluids have been extensively used in a wide variety of engineering applications. For heat transfer processes, this has been primarily driven by the potential of developing fluids with significantly-increased conductive and convective heat transfer properties. Specific emphasis in boiling phenomena and absorption and conversion of radiation are some examples of the possible utilizations of nanofluids. Other non-heat transfer applications that have considered the use of nanofluids include emerging synthesis techniques, mass transport, optics, consumer goods, electronics, and surfaces and catalysts.

This Special Issue is developed to review the current state-of-the-art of nanofluids due to the rapid advances and increasing control in nano-material fabrication techniques. Because of the complex behavior of nanofluids, fundamental and applied studies in nanofluids are welcome. Papers focusing on the expansion of nanofluid applications in diverse, multidisciplinary research and development are also welcomed.

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Message from the Editor-in-Chief

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